

Technical Data Sheet

Water Soluble Flux

ASF201

Halide Contents

≤ 0.05
(wt%)

Test methods
JIS Z 3197 8.1.4.2.1

Viscosity

30.0 ± 10
Reference Value
(Pa·s)

Test methods
Rheometer

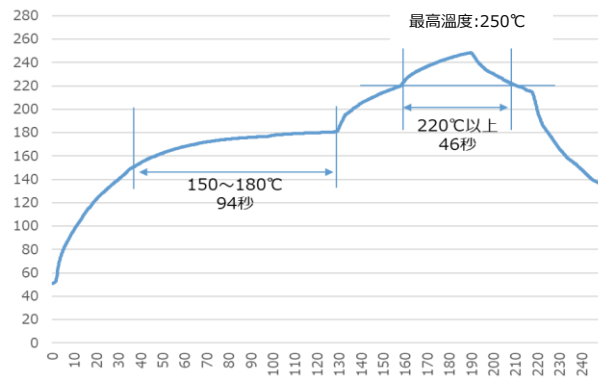
Thixotropy

0.4 ± 0.2
Reference Value

Test methods
Rheometer

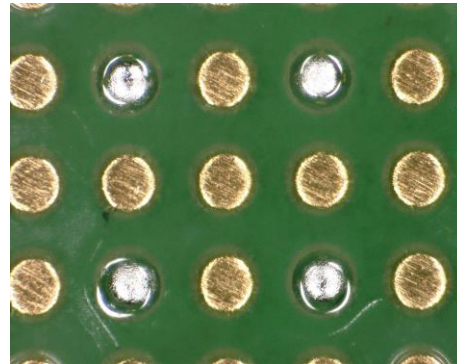
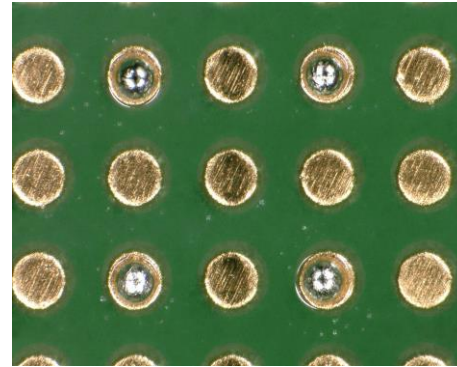
- Pad information:
(left) diameter 0.3mm
(right) diameter 0.5mm
- material: Au-coating

- Heat profile:
150~180°C 94 seconds
220°C 46 seconds
Peak: 250°C



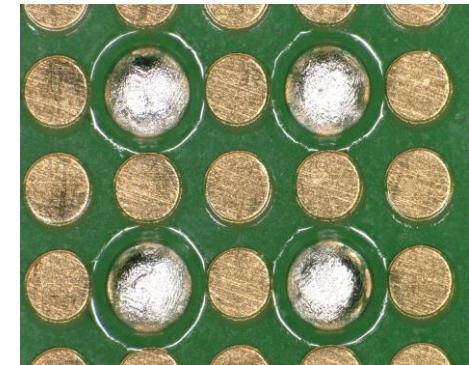
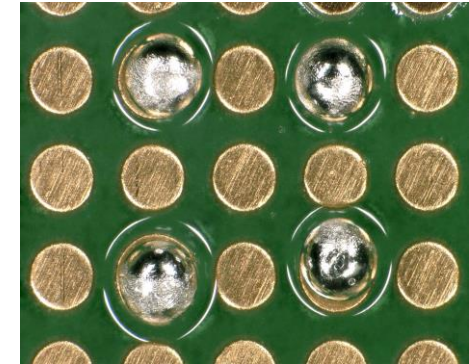
Before
Heating

Solder ball size $\Phi 200\mu\text{m}$



After
Heating

Solder ball size $\Phi 600\mu\text{m}$

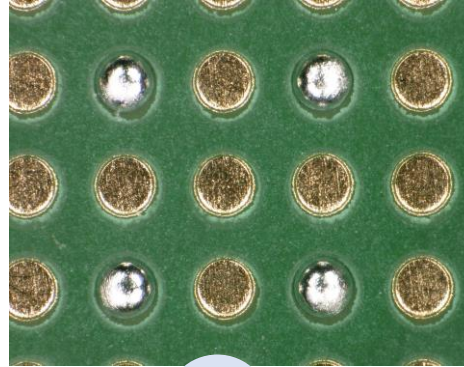


⇒ Excellent Solderability

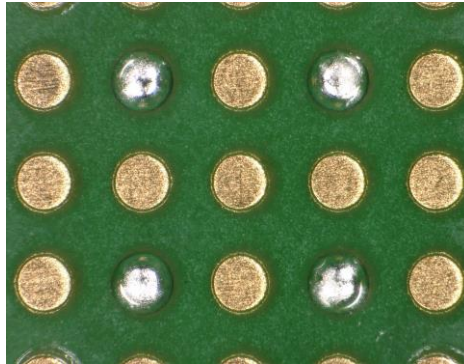
- Condition:
Water temperature 60℃
By Ultrasonic cleaning 4 min

Before
Cleaning

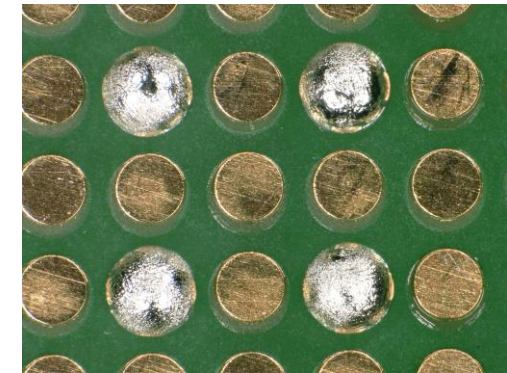
Solder ball size $\Phi 200\mu\text{m}$



After
Cleaning



Solder ball size $\Phi 600\mu\text{m}$



⇒ Excellent Washability

- ① Do not use this product for other purposes except soldering.
- ② Do not touch this product directly. In case of skin contact, wipe with tissue or cloth with alcohol or appropriate solvent then wash by soap water.
- ③ Do not inhale fume generated from this product. Adequate ventilation is required.
- ④ Recommended storage condition and quality guarantee period are as follows:
Keep refrigerated (below 10°C) : 3 months from manufacturing date.
- ⑤ When it backs to room temperature (24°C), avoid to heat too rapidly.
Keep it at room temperature and wait for 1-2 hours. Do not use it when it is refrigerated.
- ⑥ Chlorinated or fluorinated solvents or other type of solvents will cause degrading of solderability.
Please be careful in cleaning of supplying tools.
- ⑦ Please keep it away from any fire source in working place or store room.